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Improvement in Photosensitivity of Dumbbell-Shaped Graphene Nanoribbon Structures by Using Asymmetric Metallization Technique

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Acceleration Mechanism of Intergranular Cracking of SUS316L under Creep-Fatigue Loading at Elevated Temperatures

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Molecular Dynamics Analysis of the Acceleration of the Degradation of the Strength of A Grain Boundary Under Creep-Fatigue Loads

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Creep-Fatigue Damage of Heat-Resistant Alloys Caused by the Local Lattice Mismatch-Induced Acceleration of the Generation and Accumulation of Dislocations and Vacancies


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Detachable Fine Bump Connection using Multi-Walled Carbon-Nanotube Bundles for 3D Semiconductor Modules

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Effect of Tensile Strain on Electron Transport Properties of Dumbbell-Shape Graphene Nanoribbons With Metallic-Semiconducting Interfaces

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Crystallinity-Induced Acceleration of Intergranular Cracking in Thin-Film Interconnections under High Current Density

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